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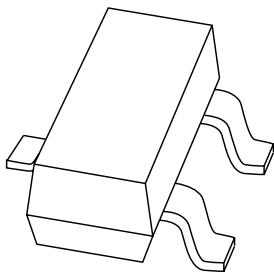
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via [salesaddresses@nexperia.com](mailto:salesaddresses@nexperia.com)). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# DATA SHEET



**BF550**

**PNP medium frequency transistor**

Product data sheet  
Supersedes data of 1999 Apr 15

2004 Jan 16

# PNP medium frequency transistor

# BF550

### FEATURES

- Low current (max. 25 mA)
- Low voltage (max. 40 V).

### APPLICATIONS

- Medium frequency applications in thick and thin film circuits.

### DESCRIPTION

PNP medium frequency transistor in a SOT23 plastic package.

### MARKING

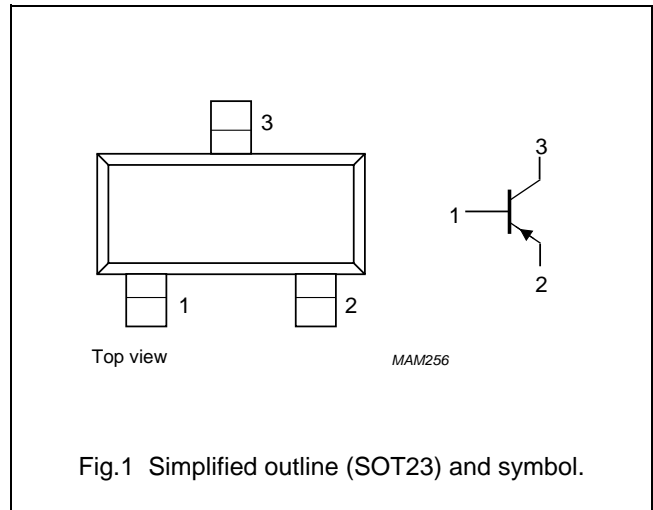
TYPE NUMBER	MARKING CODE <sup>(1)</sup>
BF550	LA*

### Note

- \* = p : Made in Hong Kong.  
 \* = t : Made in Malaysia.  
 \* = W : Made in China.

### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BF550	–	plastic surface mounted package; 3 leads	SOT23

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	–	–40	V
V <sub>CEO</sub>	collector-emitter voltage	open base	–	–40	V
V <sub>EBO</sub>	emitter-base voltage	open collector	–	–4	V
I <sub>C</sub>	collector current (DC)		–	–25	mA
I <sub>CM</sub>	peak collector current		–	–25	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	–	250	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–	150	°C
T <sub>amb</sub>	operating ambient temperature		–65	+150	°C

### Note

1. Transistor mounted on an FR4 printed-circuit board.

## PNP medium frequency transistor

BF550

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

**Note**

1. Transistor mounted on an FR4 printed-circuit board.

**CHARACTERISTICS**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0; V_{CB} = -30\text{ V}$	–	–	–50	nA
$I_{EBO}$	emitter cut-off current	$I_C = 0; V_{EB} = -3\text{ V}$	–	–	–100	nA
$h_{FE}$	DC current gain	$I_C = -1\text{ mA}; V_{CE} = -10\text{ V}$	50	–	–	
$V_{BE}$	base-emitter voltage	$I_C = -1\text{ mA}; V_{CE} = -10\text{ V}$	–	750	–	mV
$C_{re}$	feedback capacitance	$I_C = -1\text{ mA}; V_{CB} = -10\text{ V}; f = 1\text{ MHz}$	–	0.5	–	pF
$f_T$	transition frequency	$I_C = -1\text{ mA}; V_{CE} = -10\text{ V}; f = 100\text{ MHz}$	–	325	–	MHz

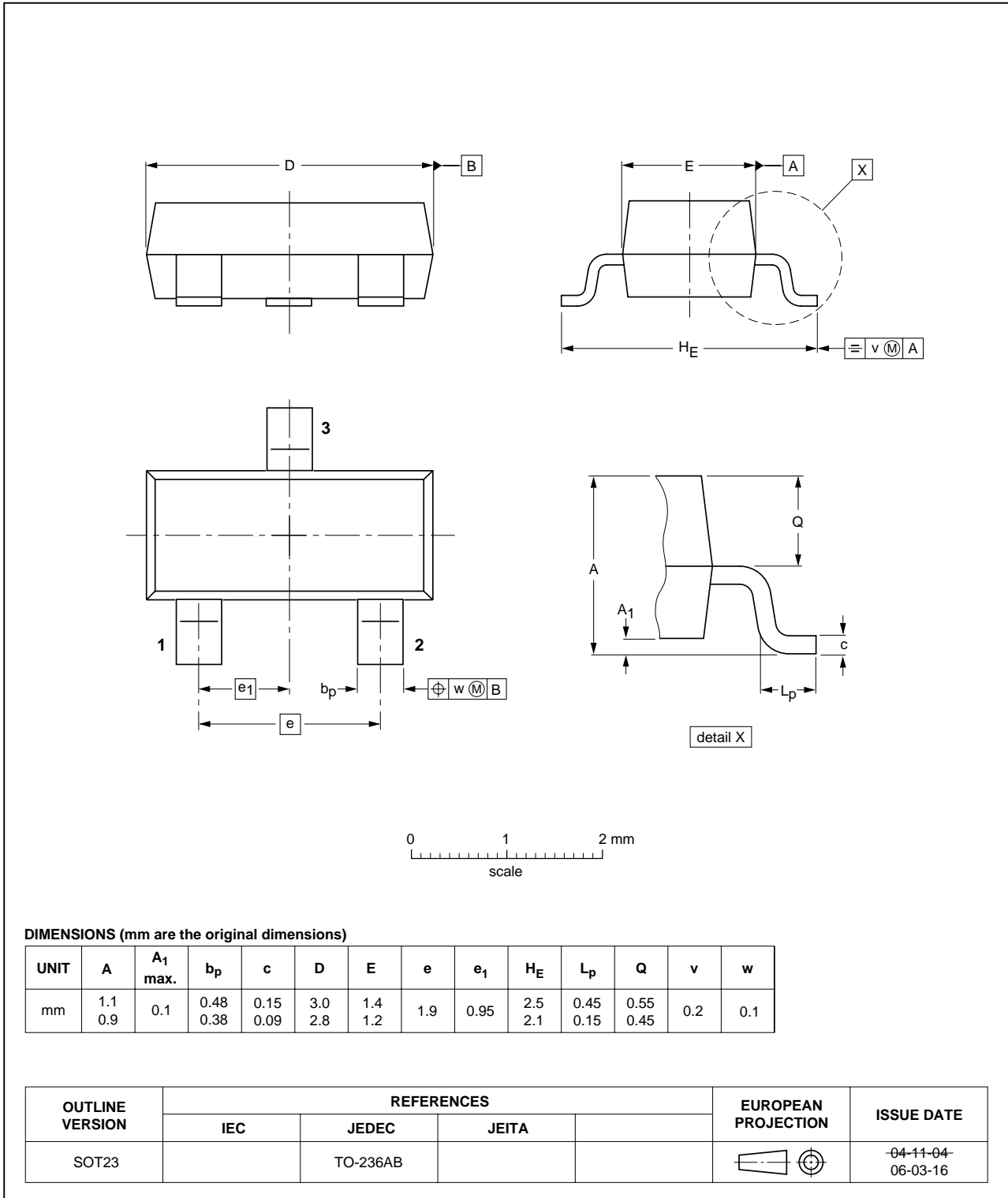
PNP medium frequency transistor

BF550

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



# PNP medium frequency transistor

BF550

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

### Notes

1. Please consult the most recently issued document before initiating or completing a design.
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# ***NXP Semiconductors***

## **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

## **Contact information**

For additional information please visit: <http://www.nxp.com>

For sales offices addresses send e-mail to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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